

# 30V N-Channel Enhancement Mode Power MOSFET

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# **Description**

WMQ30N03T2 uses advanced power trench technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

#### **Features**

•  $V_{DS} = 30 \text{ V}, I_D = 30 \text{ A}$ 

 $R_{DS(on)} < 6.3 \text{m}\Omega$  @  $V_{GS} = 10 \text{ V}$ 

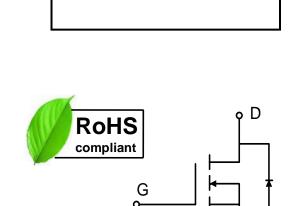
 $R_{DS(on)} < 9.0 \text{m}\Omega$  @  $V_{GS} = 4.5 \text{V}$ 

- Green Device Available
- Low Gate Charge
- Advanced High Cell Density Trench Technology
- 100% EAS Guaranteed



- Power Management Switches
- DC/DC Converter

## **Absolute Maximum Ratings**



PDFN3030-8L

Parameter		Symbol	Value	Unit	
Drain-Source Voltage		V <sub>DS</sub>	30	V	
Gate-Source Voltage		V <sub>GS</sub>	±20	V	
	T <sub>C</sub> =25°C	I <sub>D</sub>	30		
Continuous Drain Current@10V1	T <sub>C</sub> =100°C		24	^	
	T <sub>A</sub> =25°C		20	A	
	T <sub>A</sub> =70°C		15	1	
Pulsed Drain Current <sup>2</sup>		I <sub>DM</sub>	100	Α	
Single Pulse Avalanche Energy³		EAS	28.8	mJ	
Avalanche Current		las	24	Α	
Total Power Dissipation <sup>4</sup> T <sub>C</sub> =25°C		P <sub>D</sub>	24	W	
Operating Junction and Storage Temperature Range		Тл, Тата	-55 to+150	°C	

#### **Thermal Characteristics**

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient <sup>1</sup>	$R_{\theta JA}$	60	°C/W
Thermal Resistance from Junction-to-Case <sup>1</sup>	Rелс	5.2	°C/W



#### Electrical Characteristics T<sub>c</sub> = 25°C, unless otherwise noted

Parameter		Symbol	Symbol Test Conditions		Тур.	Max.	Unit	
Static Characteristics								
Drain-Source Breakdown Voltage		V <sub>(BR)DSS</sub>	$V_{GS} = 0V, I_D = 250\mu A$	30	-	-	V	
Gate-body Leakage current		Igss	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±100	nA	
Zero Gate Voltage Drain Current	T <sub>J</sub> =25°C		V 04V V 0V	-	-	1	μА	
	T <sub>J</sub> =55°C	I <sub>DSS</sub>	$V_{DS} = 24V$ , $V_{GS} = 0V$	-	-	5		
Gate-Threshold Voltage		V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1.2	-	2.5	V	
Drain-Source On-Resistance <sup>2</sup>		R <sub>DS(on)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 20A	-	5	6.3	mΩ	
			V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 15A	-	8	9.5		
Forward Transconductance		<b>g</b> fs	$V_{DS} = 5V, I_{D} = 30A$	-	43	-	S	
Dynamic Characteristic	s			•				
Input Capacitance		Ciss	iss		814	-	pF	
Output Capacitance  Reverse Transfer Capacitance		Coss	V <sub>DS</sub> = 15V, V <sub>GS</sub> =0V, f =1MHz	-	398	-		
		C <sub>rss</sub>		-	62	-		
Switching Characterist	ics			•		•		
Gate Resistance		Rg	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$	-	1.7	-	Ω	
Total Gate Charge		Qg		-	8	-	nC	
Gate-Source Charge		Q <sub>gs</sub>	$V_{GS} = 4.5V, V_{DS} = 15V, I_{D} = 15A$	-	2.4	-		
Gate-Drain Charge		$Q_{gd}$		-	3.2	-		
Turn-On Delay Time		t <sub>d(on)</sub>		-	7.1	-	. nS	
Rise Time		t <sub>r</sub>	$V_{GS} = 10V, V_{DD} = 15V,$	-	40	-		
Turn-Off Delay Time Fall Time		t <sub>d(off)</sub>	$R_G = 3.3\Omega, I_D = 15A$	-	15	-		
		t <sub>f</sub>		-	6	-		
Drain-Source Body Dio	de Charac	teristics		ı		ı		
Diode Forward Voltage <sup>2</sup>		V <sub>SD</sub>	I <sub>S</sub> = 1A, V <sub>GS</sub> = 0V	-	-	1.0	V	
Continuous Source Current <sup>1</sup>		Is	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current	-	-	24	Α	
Body Diode Reverse Recovery Time		t <sub>rr</sub>		-	34	-	nS	
Body Diode Reverse Recovery Charge		Q <sub>rr</sub>	I <sub>F</sub> = 20A, dl/dt = 100A/μs	-	15	-	nC	

#### Note:

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2%
- 3. The EAS data shows Max. rating . The test condition is  $V_{DD}$ =25V,  $V_{GS}$ =10V, L=0.1mH,  $I_{AS}$ =24A
- 4.The power dissipation is limited by 150°C junction temperature
- 5. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.



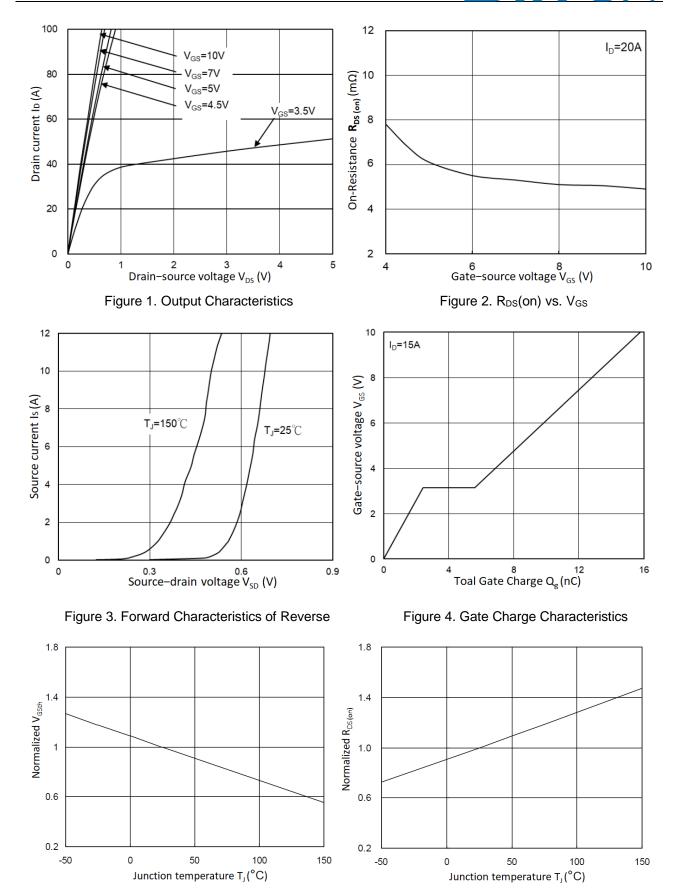


Figure 5. Normalized V<sub>GSth</sub> vs. T<sub>J</sub>

Figure 6. Normalized R<sub>DS(on)</sub> vs. T<sub>J</sub>



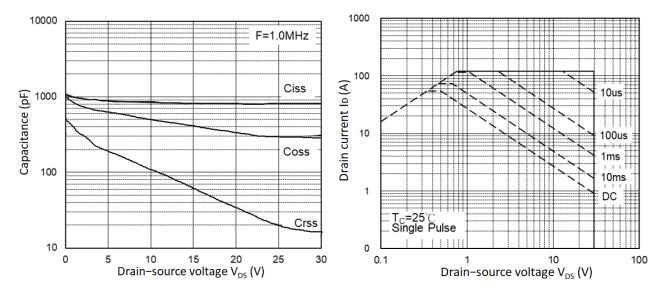


Figure 7. Capacitance Characteristics

Figure 8. Safe Operating Area

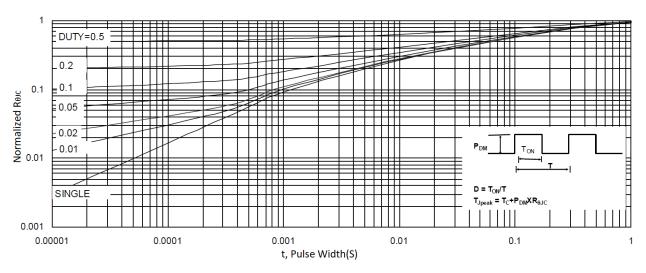


Figure 9. Normalized Maximum Transient Thermal Impedance

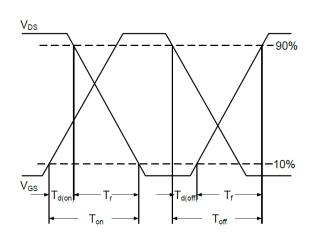


Figure 10. Switching Time Waveform

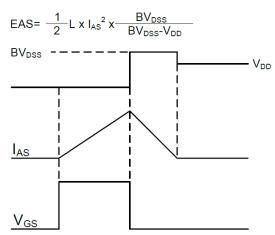


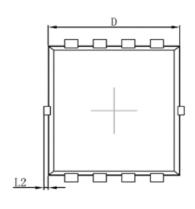
Figure 11. Unclamped Inductive Switching

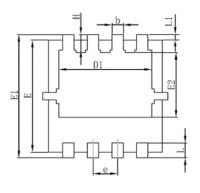
Waveform

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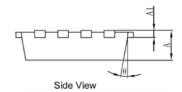


#### **Mechanical Dimensions for PDFN3030-8L**





Top View Bottom View



### **COMMON DIMENSIONS**

SYMBOL	MM			
	MIN	MAX		
А	0.70	0.85		
A1	0.10	0.25		
D	2.90	3.25		
D1	2.25	2.65		
E	2.90	3.20		
E1	3.10	3.45		
E2	1.54	1.98		
b	0.20	0.40		
е	0.60	0.70		
L	0.30	0.50		
L1	0.13BSC			
L2	0.00	0.15		
Н	0.20	0.65		
θ	0°	14°		

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### **Ordering Information**

Part	Package	Marking	Packing method
WMQ30N03T2	PDFN3030-8L	Q30N03	Tape and Reel

#### **Marking Information**



Q30N03 = Device code WWXX XXX= Date code

#### **Contact Information**

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